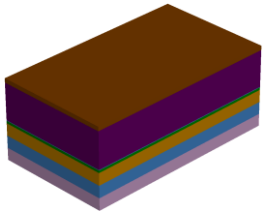
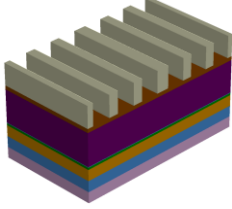


# AVS 69 abstract - Illustrations

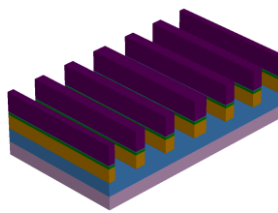
1. MI stack deposition



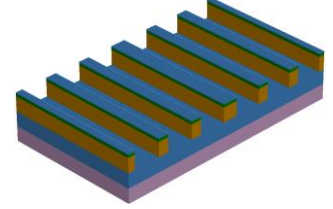
2. MI litho



3. MI etch

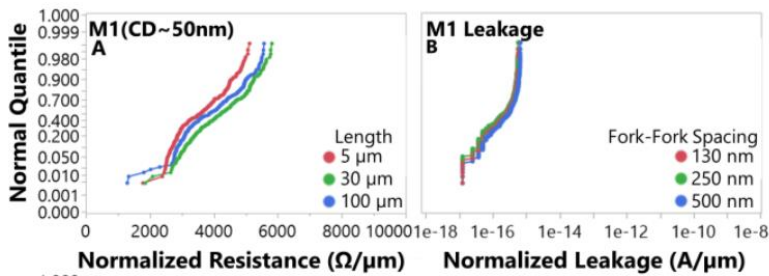
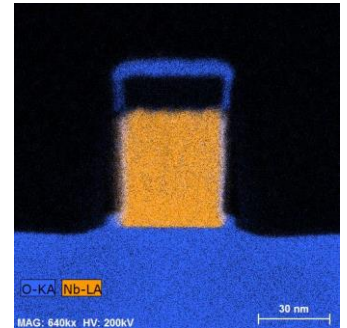
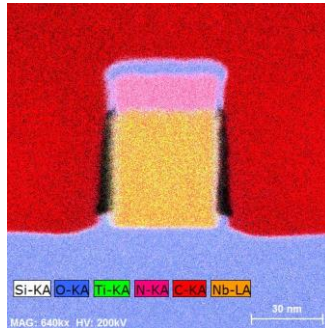
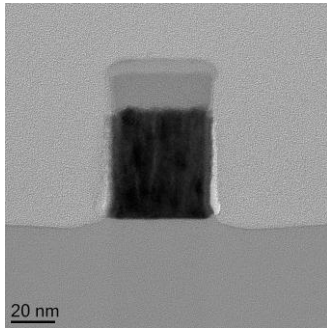
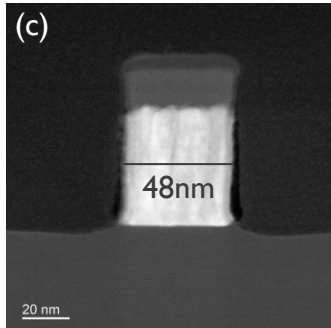
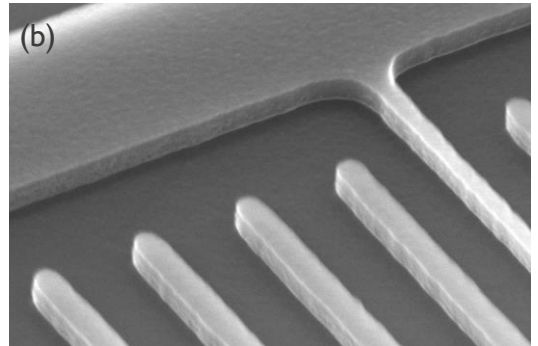
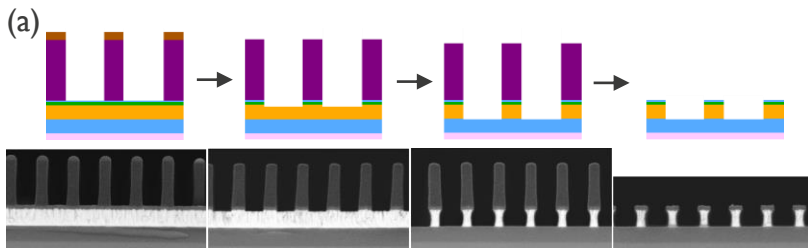


4. Mask stripping

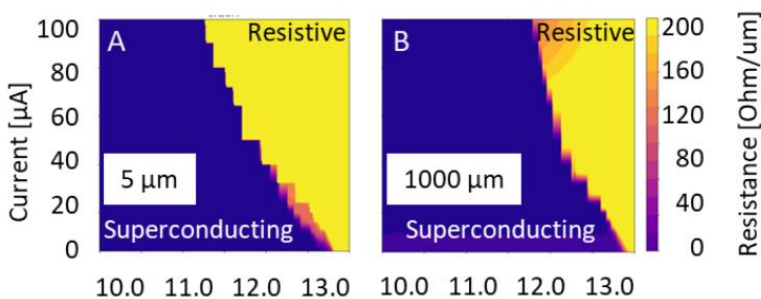


**Figure 1 :** Level-I metal (MI) BEOL integration scheme.

**Figure 2 :** Examples of inspections for MI etch development : (a) XSEM, (b) FIB-SEM and (c) TEM-EDS pictures.



**Figure 3 :** (a) Normalized room temp resistance of MI  $Nb_xTi_{(1-x)}N$  lines with 50nm CD. (b) Leakage measurement of MI Fork-Fork structures with 130, 250 and 500nm Fork-Fork spacing.



**Figure 4 :** Shmoos plots showing  $T_c$  and critical current for  $Nb_xTi_{(1-x)}N$  lines with 50nm CD and (a) 5 and (b) 1000  $\mu m$  in length.